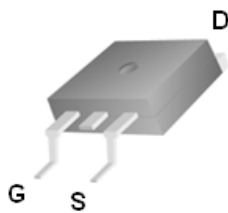


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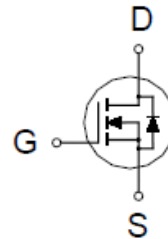
## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
100V	9.5m $\Omega$ @ $V_{GS} = 10V$	80A



TO-263



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	$I_D$	80	A
	$T_C = 100\text{ }^\circ\text{C}$		50	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	250	
Avalanche Current		$I_{AS}$	72	
Avalanche Energy	$L = 0.3\text{mH}$	$E_{AS}$	797	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	125	W
	$T_C = 100\text{ }^\circ\text{C}$		50	
Operating Junction & Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$
Lead Temperature( <sup>1</sup> / <sub>16</sub> " from case for 10 sec.)		$T_L$	275	

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

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## N-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS (T<sub>c</sub> = 25 °C, Unless Otherwise Noted)

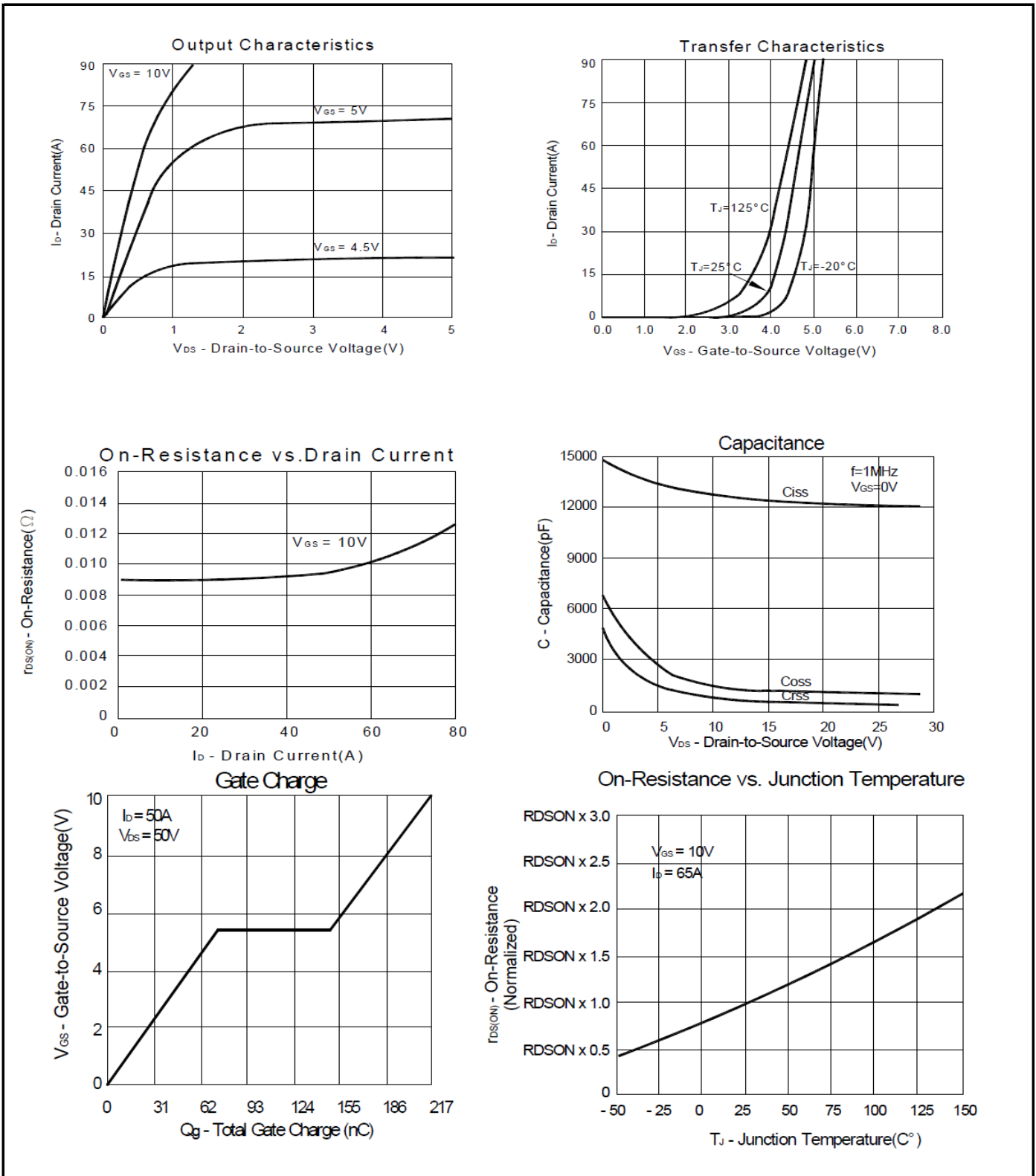
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	100			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.5	2.3	4.0	V
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V			±250	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V			1	μA
		V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125 °C			10	
On-State Drain Current <sup>1</sup>	I <sub>D(ON)</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 10V	80			A
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 65A		8.2	9.5	mΩ
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 25V, I <sub>D</sub> = 65A		90		S
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1MHz		12000		pF
Output Capacitance	C <sub>oss</sub>			900		
Reverse Transfer Capacitance	C <sub>rss</sub>			500		
Total Gate Charge <sup>2</sup>	Q <sub>g</sub>	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 50A		217		nC
Gate-Source Charge <sup>2</sup>	Q <sub>gs</sub>			71		
Gate-Drain Charge <sup>2</sup>	Q <sub>gd</sub>			75		
Turn-On Delay Time <sup>2</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 50V, I <sub>D</sub> ≅ 50A, V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 25Ω		23		nS
Rise Time <sup>2</sup>	t <sub>r</sub>			205		
Turn-Off Delay Time <sup>2</sup>	t <sub>d(off)</sub>			94		
Fall Time <sup>2</sup>	t <sub>f</sub>			190		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 °C)</b>						
Continuous Current	I <sub>S</sub>				80	A
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = 50A, V <sub>GS</sub> = 0V			1.3	V
Reverse Recovery Time	t <sub>rr</sub>			80		nS
Reverse Recovery Charge	Q <sub>rr</sub>			220		nC

<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

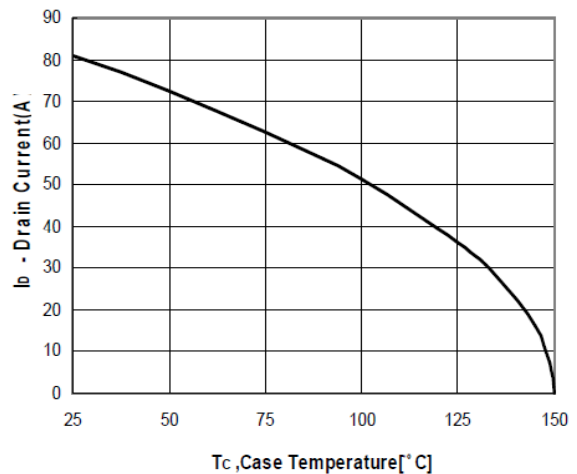
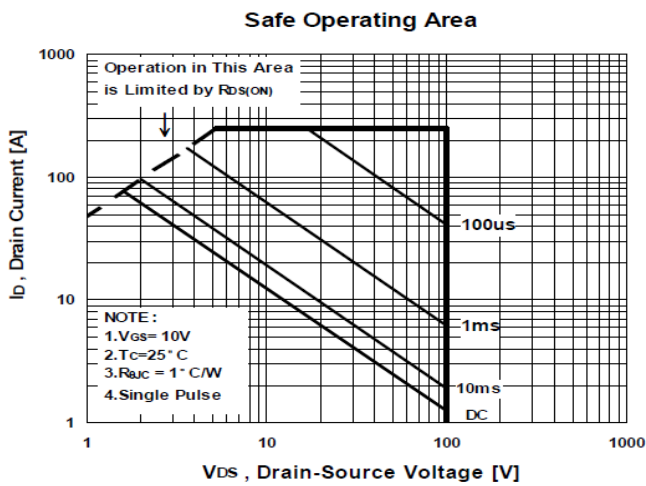
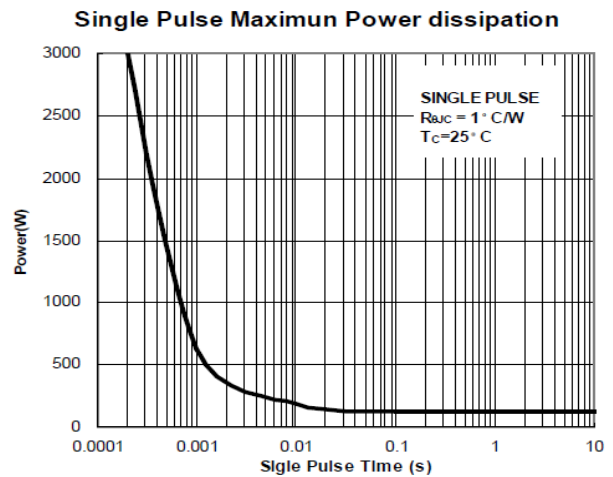
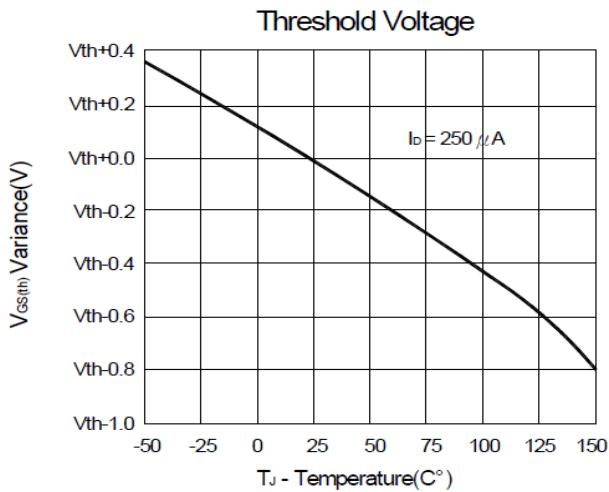
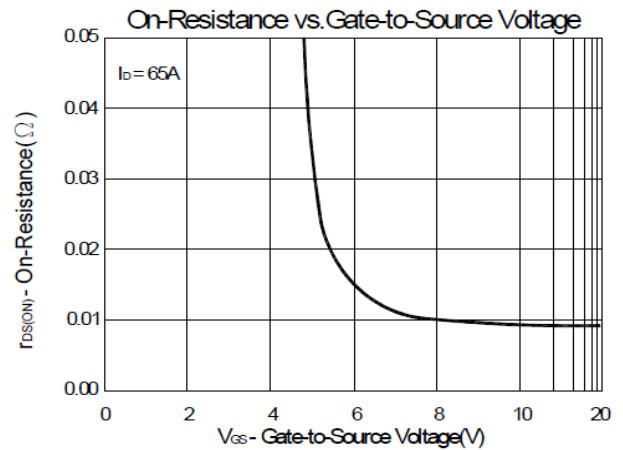
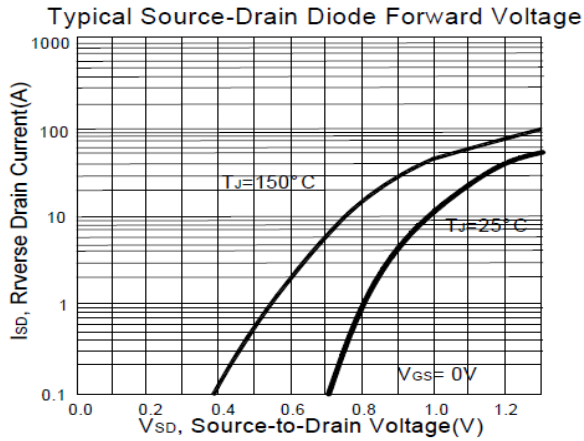
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## N-Channel Enhancement Mode MOSFET



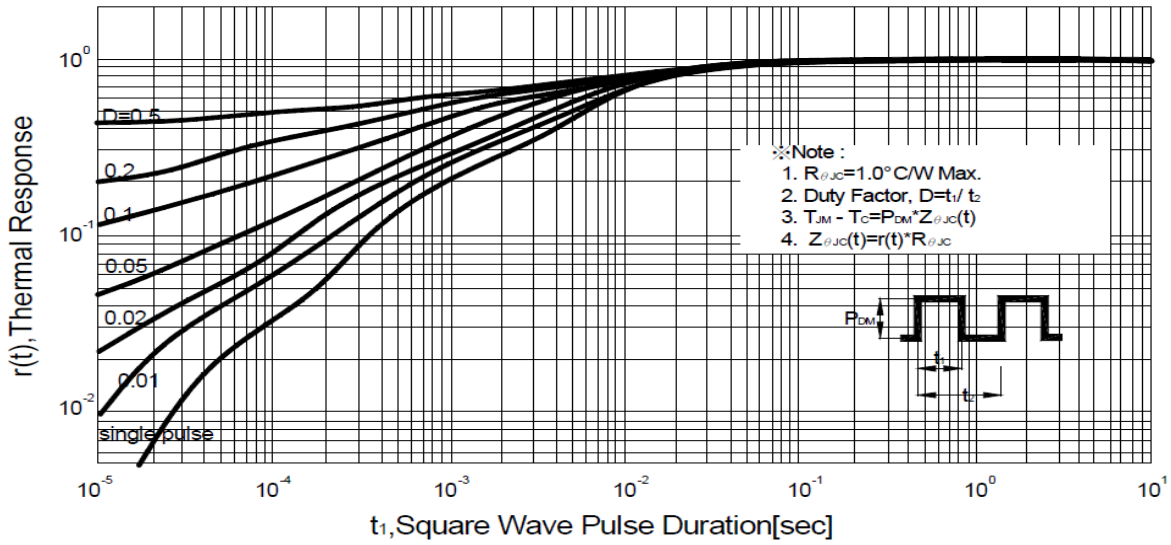
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## N-Channel Enhancement Mode MOSFET



**P0910AS**  
**N-Channel Enhancement Mode MOSFET**

Transient Thermal Response Curve



# P0910AS

## N-Channel Enhancement Mode MOSFET

### Package Dimension

### TO-263 (D<sup>2</sup>PAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.2		4.8	e	4.08	5.08	6.08
A1	0		0.3	E	9.8		10.55
b	0.71		1.06	E1	6.9		8.7
b2	1.07		1.47	H	14.2		15.8
C	0.3		0.69	L	1.2		2.79
C2	1.15		1.45	L1	1		1.65
D	8.3		9.4	L2	1.2		1.78
D1	6.37		8.23				

